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Taniguchi et al.

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(54) **ADHESIVE TAPE FOR SEMICONDUCTOR MANUFACTURING**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
156/235, 248; 428/343, 345, 353, 355 R;
438/114, 455, 460, 463

See application file for complete search history.

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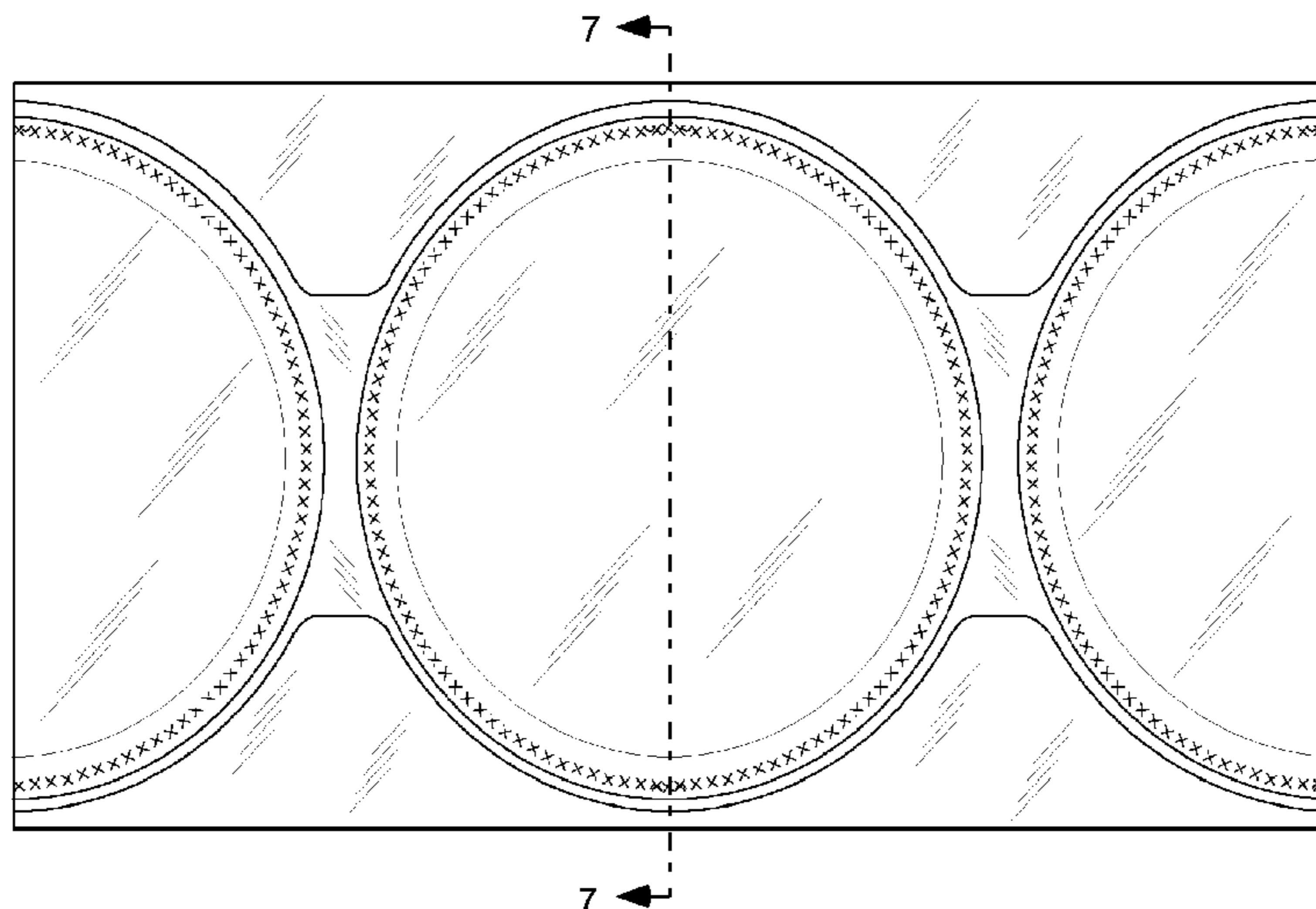
(57) **CLAIM**

The ornamental design for an adhesive tape for semiconductor manufacturing, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of our new design;
FIG. 2 is a bottom plan view;
FIG. 3 is a left side view;
FIG. 4 is a right side view;
FIG. 5 is a rear side view;
FIG. 6 is a front side view;
FIG. 7 is a cross sectional view taken at line 7-7 of FIG. 1;
FIG. 8 is an exploded view; and,
FIG. 9 is an enlarged view of the lower and left portion of the claimed design shown in FIG. 1 for completeness of illustration.

1 Claim, 4 Drawing Sheets



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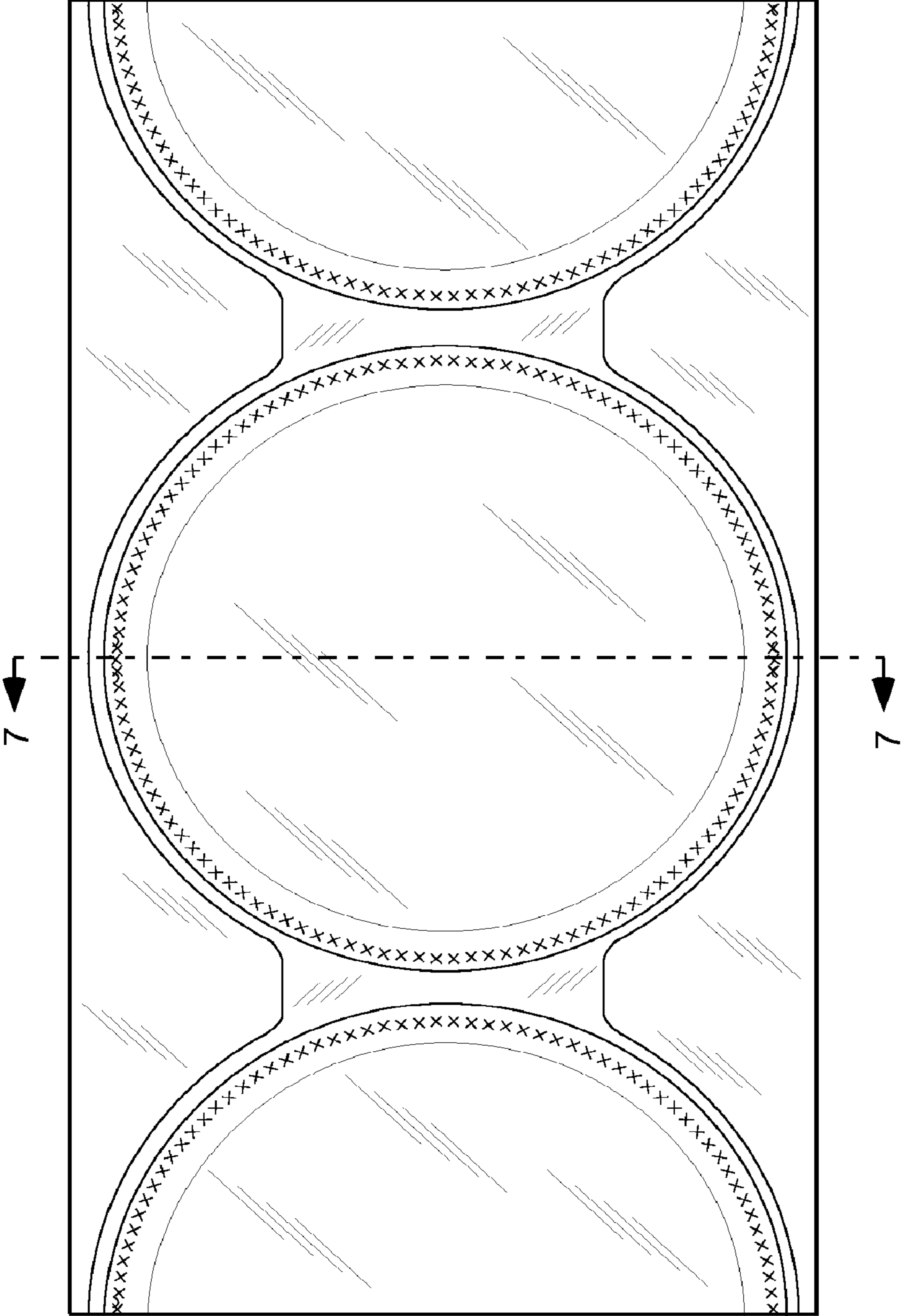


Fig. 1

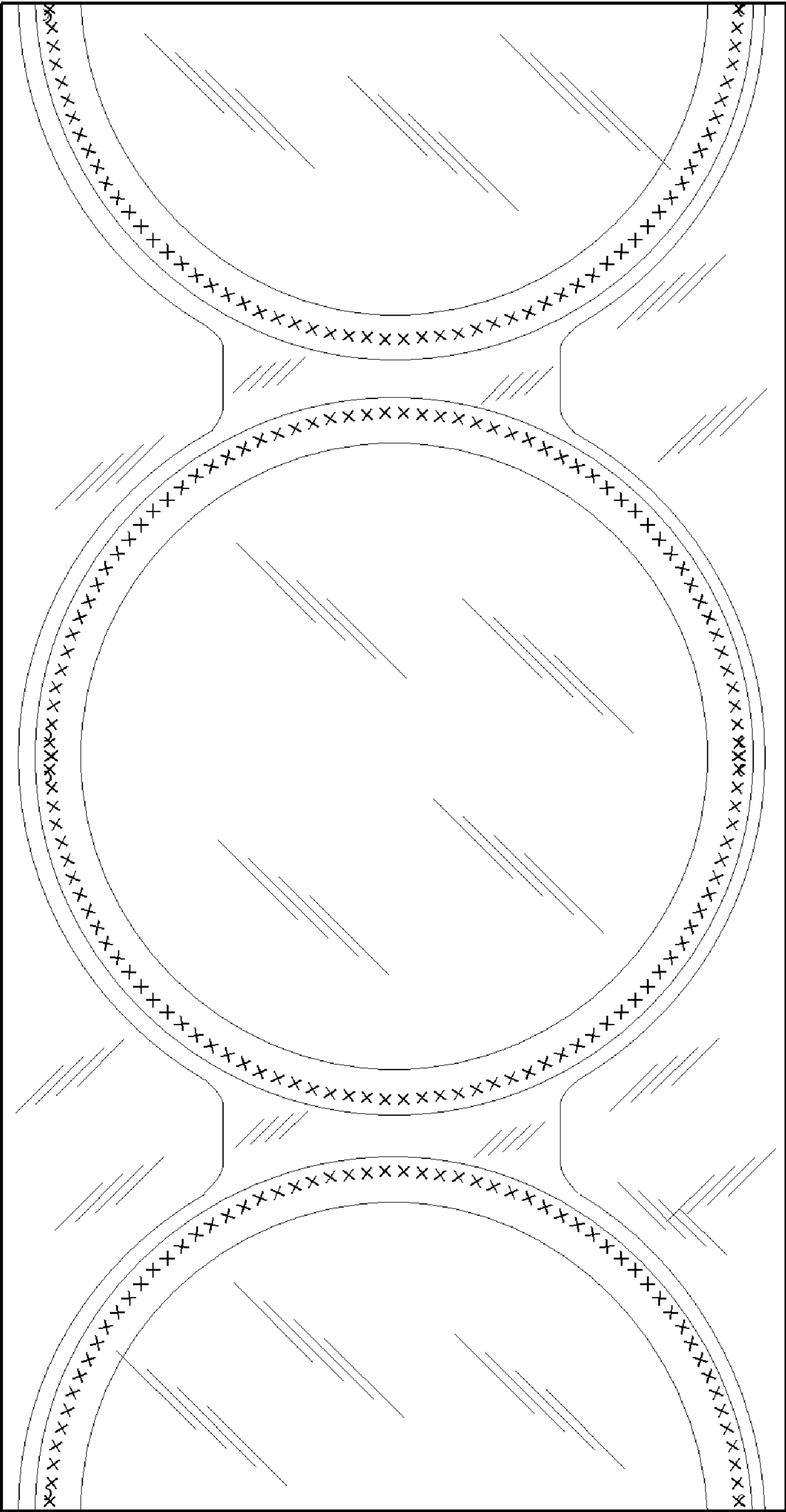


Fig. 2



Fig. 3



Fig. 4



Fig. 7



Fig. 5



Fig. 6

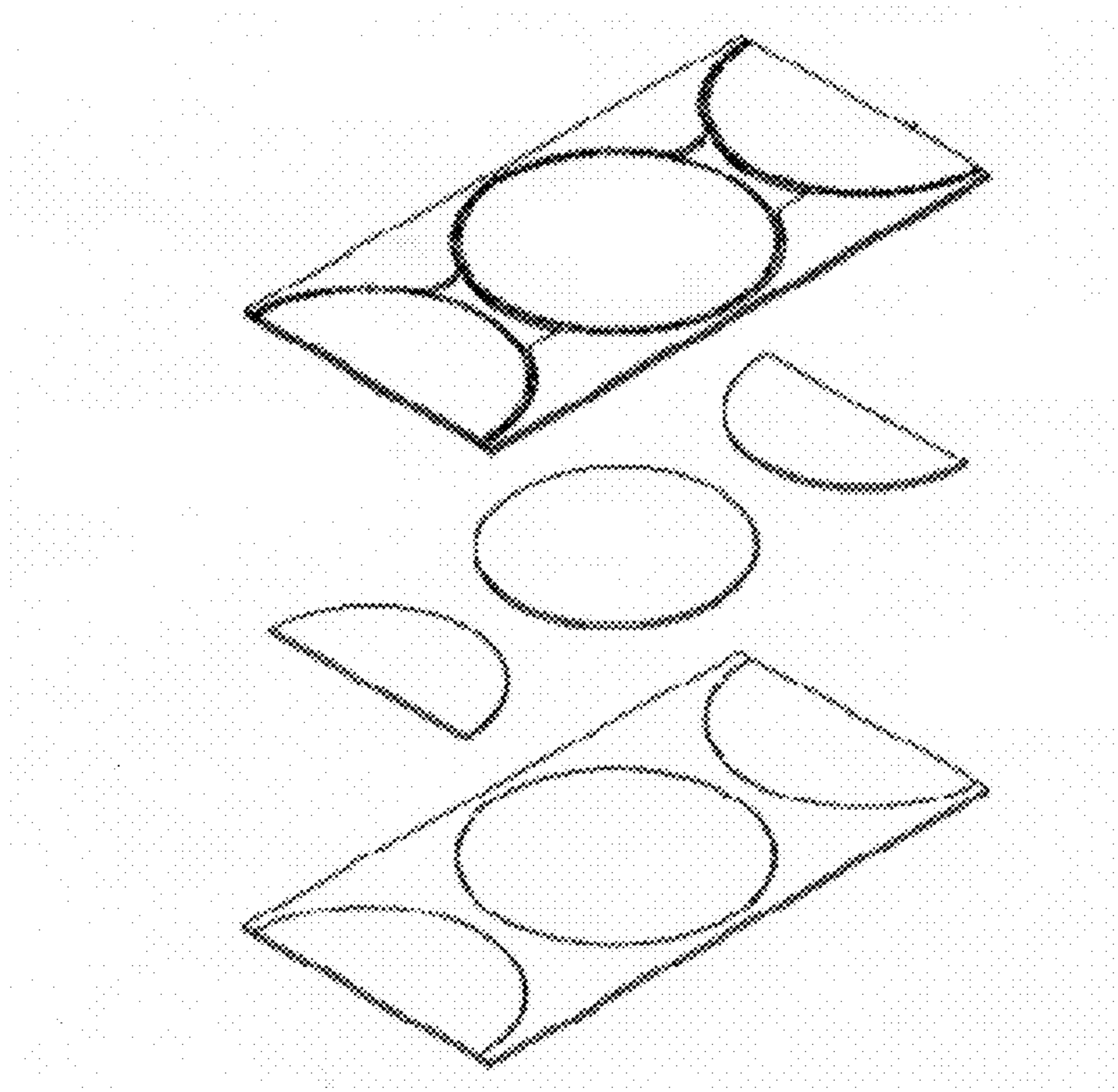


Fig. 8

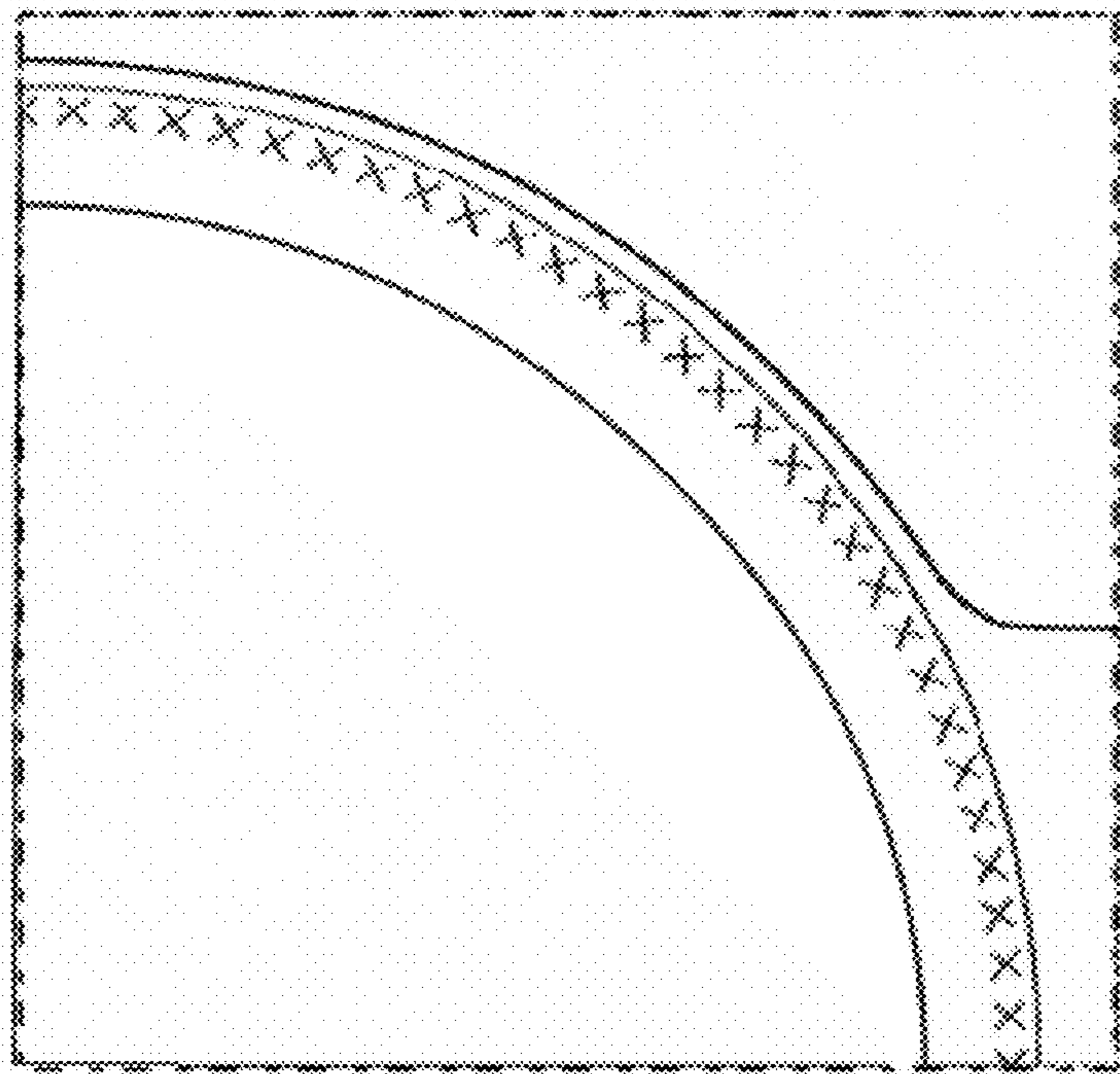


Fig. 9